

## **HAT1110R**

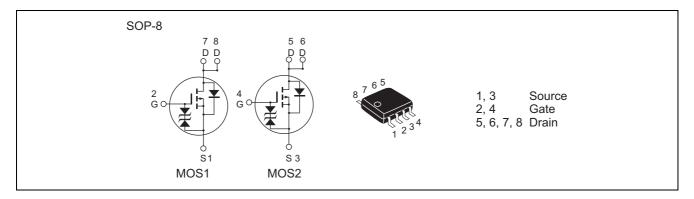
# Silicon P Channel Power MOS FET Power Switching

REJ03G0416-0200 Rev.2.00 Oct.07.2004

#### **Features**

- Capable of -4.5 V gate drive
- Low drive current
- High density mounting

#### **Outline**



### **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit	
Drain to source voltage	V <sub>DSS</sub>	-80	V	
Gate to source voltage	V <sub>GSS</sub>	±20	V	
Drain current	I <sub>D</sub>	<b>–</b> 1	A	
Drain peak current	I <sub>D(pulse)</sub> Note1	-6	A	
Reverse drain current	I <sub>DR</sub>	<b>–</b> 1	A	
Channel dissipation	Pch Note2	1.2	W	
Channel dissipation	Pch Note3	1.8	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

- 2. 1 Drive operation; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW  $\leq$  10 s
- 3. 2 Drive operation; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW  $\leq$  10 s

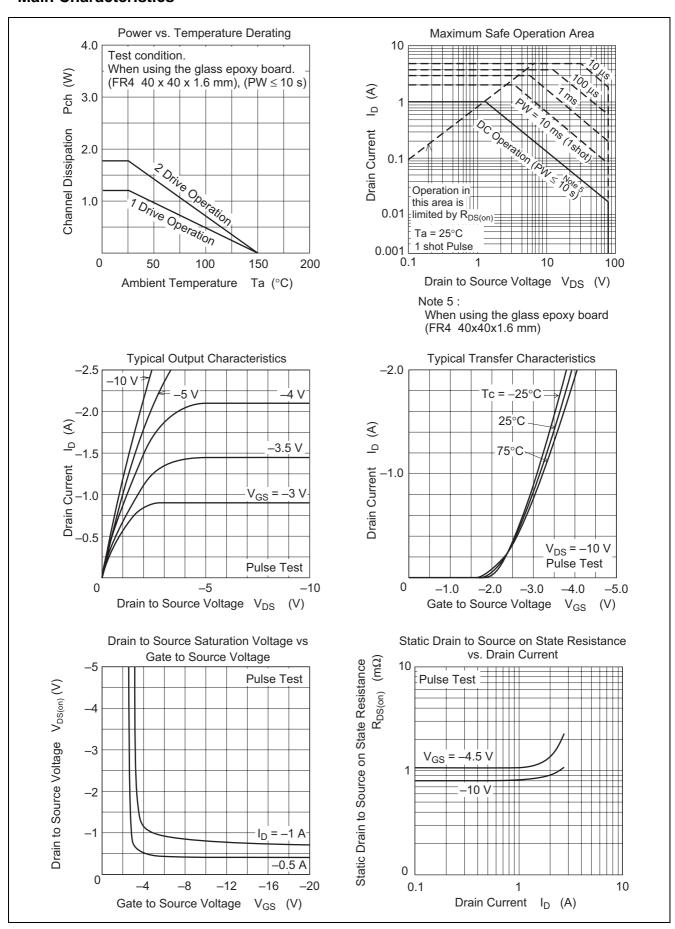
### **Electrical Characteristics**

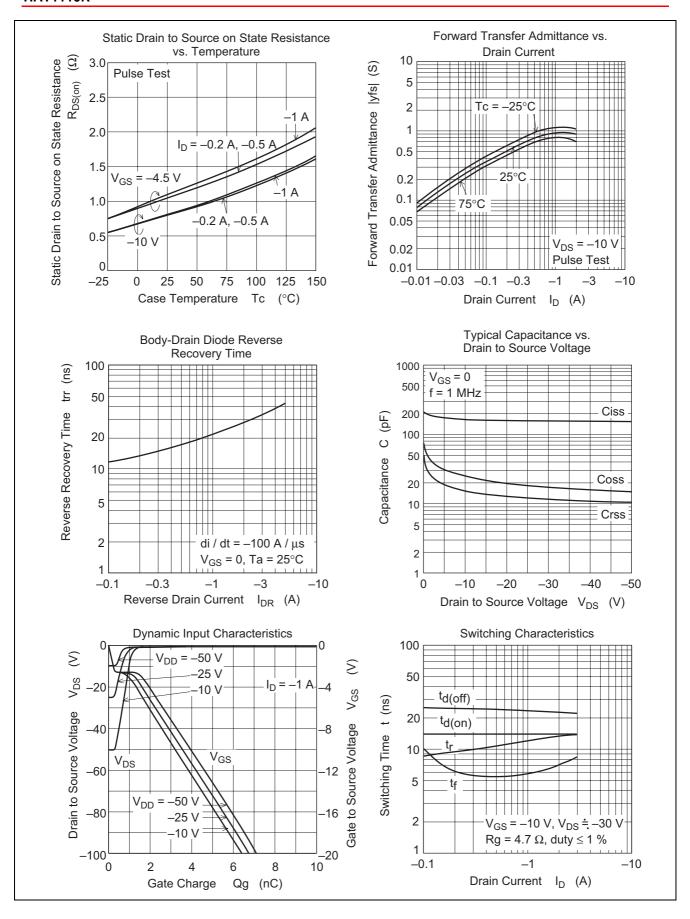
 $(Ta = 25^{\circ}C)$ 

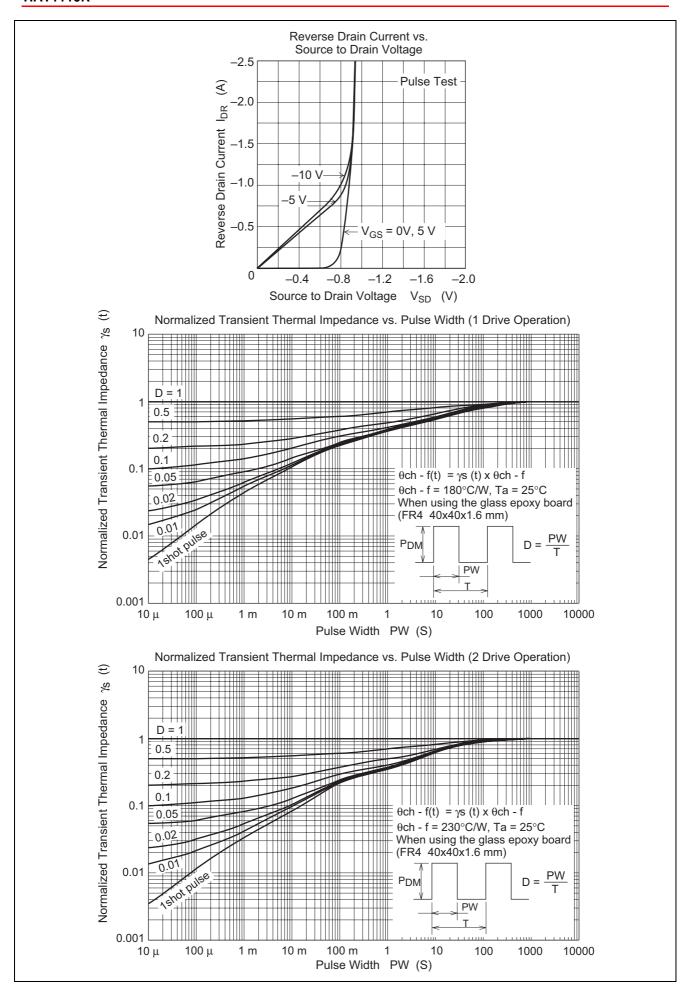
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain to source breakdown voltage	$V_{(BR)DSS}$	-80	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_		٧	$I_G = \pm 100 \mu\text{A},  V_{DS} = 0$	
Gate to source leak current	I <sub>GSS</sub>		_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$	
Zero gate voltage drain current	I <sub>DSS</sub>		_	-1	μΑ	$V_{DS} = -80 \text{ V}, V_{GS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.5	<b>V</b>	$V_{DS} = -10 \text{ V}, I_D = -1 \text{mA}$	
Static drain to source on state	R <sub>DS(on)</sub>		0.8	1.05	Ω	$I_D = -0.5 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note4}}$	
resistance	R <sub>DS(on)</sub>	_	1.02	1.38	Ω	$I_D = -0.5 \text{ A}, V_{GS} = -4.5 \text{ V}^{\text{Note4}}$	
Forward transfer admittance	y <sub>fs</sub>	0.4	0.8	1	S	$I_D = -0.5 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note4}}$	
Input capacitance	Ciss		170	1	pF	$V_{DS} = -10 \text{ V}$	
Output capacitance	Coss	_	24	_	pF	$V_{GS} = 0$	
Reverse transfer capacitance	Crss	_	16	_	pF	f = 1MHz	
Total gate charge	Qg	_	3.6	_	nC	V <sub>DD</sub> = -25 V	
Gate to source charge	Qgs	_	0.3	_	nC	$V_{GS} = -10 \text{ V}$	
Gate to drain charge	Qgd	_	0.7	_	nC	I <sub>D</sub> = -1.0 A	
Turn-on delay time	t <sub>d(on)</sub>	_	14	_	ns	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$	
Rise time	t <sub>r</sub>	_	12	_	ns	$V_{DD} \approx -30 \text{ V}$	
Turn-off delay time	t <sub>d(off)</sub>		25	_	ns	$R_L = 60 \Omega$	
Fall time	t <sub>f</sub>		5.5	_	ns	$R_g = 4.7 \Omega$	
Body-drain diode forward voltage	$V_{DF}$	_	-0.86	-1.12	V	IF = -1.0 A, V <sub>GS</sub> = 0 Note4	
Body–drain diode reverse recovery time	t <sub>rr</sub>	_	21	_	ns	IF = $-1.0 \text{ A}$ , $V_{GS} = 0$ diF/ dt = $100 \text{ A/}\mu\text{s}$	

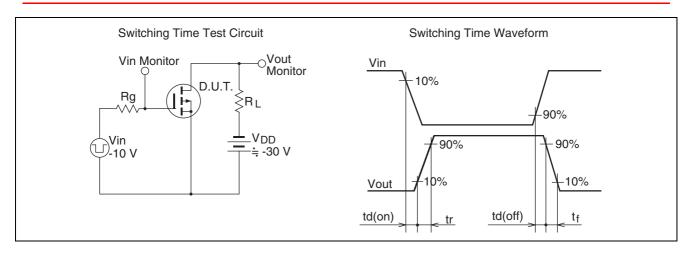
Notes: 4. Pulse test

#### **Main Characteristics**

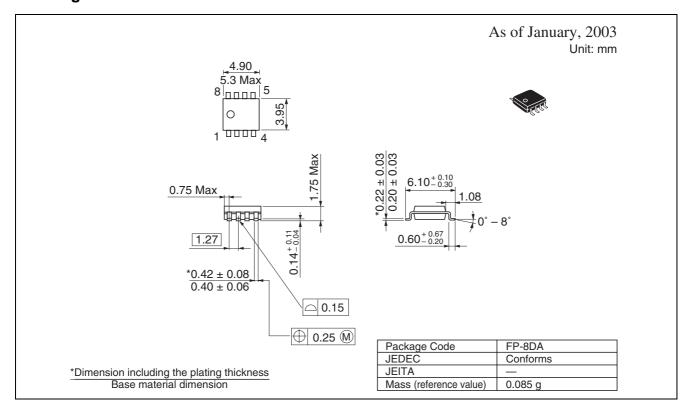








### **Package Dimensions**



### **Ordering Information**

Part Name	Quantity	Shipping Container
HAT1110R-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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- (ii) use of nontrammaple material of (iii) prevention against any maintention or misnap.

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